2. (Amended) The method according to claim 1, [characterized in that] wherein the [disturbance] varying variables which are taken into account are [the] temperatures [(T1, T2)] of the respective substrates [(S1, S2)] and [the] a temperature [(T3)] of the [coating material (7)] viscous fluid.

3. (Twice Amended) The method according to claim 1, [characterized in that] wherein the influence of the [disturbance] varying variables on the layer thickness is determined empirically.

4. (Twice Amended) The method according to claim 1, wherein a connecting means [(4)] for [connecting] joining the substrates [(S1, S2)] after the formation of bond layers and a rotary centrifugal drive [(5)] for spinning off excess bonding material between the substrates [(S1, S2)] after connection are [controlled as further controlled variables] provided and wherein the connecting means and the rotary centrifugal drive are controlled by the control means.

A1 cont'd

5. (Twice Amended) The method according to claim 1, [characterized in that] wherein the coating/bonding is controlled by [a PC/SPS (personal computer with programmable system)] means of a program run on a personal computer having a memory-programmable system.

6. (Amended) The method according to claim [5] 4, [characterized in that] wherein the dosing pump [(1)], the dosing arm [(2)], the rotary drive [(3)], and the connecting means [(4)] are operated by step motors and [that] the rotary centrifugal drive [(5)] is operated by a servomotor.

7. (Twice Amended) The method according to claim 1, [characterized in that] wherein the thickness of the coating/bond coating is measured during the process in a non-contacting manner by means of a sensor and [that] deviations from [the] a desired value of the coating thickness are readjusted automatically.

8. (Amended) The method according to claim 7, [characterized in that] wherein the desired value is a predetermined coating thickness range in the radial and tangential directions of the substrate.

9. (Twice Amended) The method according to claim 7, [characterized in that] wherein the sensor is an optical sensor.

10. (Twice Amended) [The use of the] A method [according to claim 1 in the production] of producing optical storage disks comprising utilizing the method of claim 1.

11. (Amended) The [use] method according to claim 10, [characterized in that] wherein at a desired value of the bond layer thickness of 55 μm, the deviation or tolerance of the bond layer thickness is ±10 μm in the radial direction and ± 4 μm in the tangential direction.

12. (Twice Amended) A device for [carrying out the method according to claim 1] applying coatings or layers of viscous fluid onto planar substrates, comprising

(a) sensors for measuring [disturbance] varying variables during coating/bonding of substrates,

(b) [a] means for measuring [the] a thickness of the coating/bond coating [during the process], and

(c) a processor for controlling coating/bonding in [accordance with] response to the [disturbance] varying variables and the measured thickness of the coating/bond coating by means of at least one of a controllable dosing pump [(1)], a controllable dosing arm [(2)] connected to the dosing pump and[/or by means of] a controllable rotary drive [(3, 5)] for rotating the substrates.

Please add claims 13-20 as follows:

--13. (New) The method according to claim 1 for forming bond layers between partial substrates or coatings of lacquer on substrates.--

--14. (New) A method of applying at least one layer of a viscous fluid onto at least one planar substrate, comprising:

pumping the viscous fluid with a dosing pump to a dosing arm connected to the dosing pump and positioned over the at least one substrate;

forming a first layer on a first substrate by dosing the first substrate with viscous fluid from the dosing arm;

rotating the first substrate with a rotary drive; and

controlling a thickness of the first layer formed on the first substrate to a predetermined thickness by controlling at least one of the dosing pump, a position of the dosing arm with respect to the first substrate, and a rotary speed of the rotary drive in response to variables.--

--15. (New) The method according to claim 14, wherein the variables include a temperature of the first substrate and a temperature of the viscous fluid.- -

--16. (New) The method according to claim 15, further comprising:

connecting a second substrate to the first layer of viscous fluid formed on the first substrate with a connector;

forming a second layer of viscous material between the first and second substrate by spinning off excess viscous fluid of the first layer between the first substrate and the second substrate with a rotary centrifugal drive; and

controlling a thickness of the second layer by controlling at least one of a connecting pressure of the connector and a rotary speed of the rotary centrifugal drive.- -

--17. (New) The method according to claim 16, wherein the variables include a temperature of the second substrate.- -